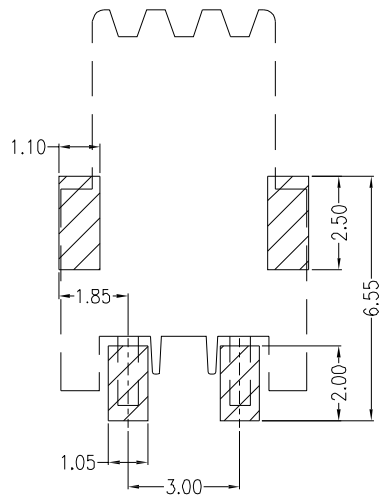
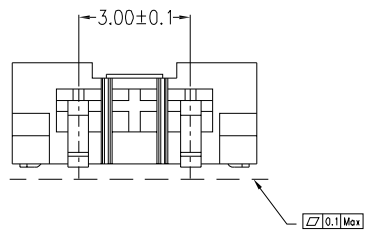


Assembly Layout

主要技术参数 Main Specifications

- 线数 (Poles): 02P
- 接触电阻 (Contact resistance):  $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance):  $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 150 V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 1000V AC/minute
- 温度范围 (Temperature Range):  $-25^{\circ}C \sim +105^{\circ}C$



Board Layout  
General Tolerance:  $\pm 0.05$

NO.	DESCRIPTION	QTY	MATERIAL	PLATING/COLOR
A	Insulator	1	LCP (UL94V-0)	Beige
B	Contacts	2	PhosphorBronze	Tin-plated
C	Solder Tab	2	PhosphorBronze	Tin-plated

UNITS mm	<b>MSTCONN</b> 深圳市德瑞电子有限公司 SHENZHEN DERUI ELECTRONIC CO., LTD.	TITLE: 3.0-2P对接插座公座		
MAT'L		PART NO.(INTENDED USE) 3.0-2P-F2MB-R	DWG NO.: 3.0-2P-F2MB-R	
FINISH	APPD:	CHKD:	SCALE 1/1	SHEET 1/1
Q'TY PCS	DR: HU 2016.09.28		REV. A	

X.± 0.3	X°.± 5°
.X± 0.25	.X°.± 2°
.XX± 0.20	.XX°.± 1°
.XXX± 0.10	.XXX°.± 0.5°